

Overview

HP ZBook Fury G1i 18 inch Mobile Workstation PC



1	ACS & ALS Sensor
2	Microphone (2)
3	IR Camera (optional)
4	Webcam
5	Camera Shutter
6	IR LED (optional)
7	Webcam LED
8	Fingerprint reader / Power button

Left

9	Security lock slot (Integrated)
10	RJ45 Ethernet port (standard)
11	USB Type-A 5Gbps signaling rate (Powered)
12	Thunderbolt™ 4 with USB Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 2.1)*
13	Headphone/mic combo jack
14	Smart Card Reader
15	3-button Touchpad

*Actual throughout may vary.

Overview



Right

1	Power Indicator LED	4	HDMI 2.1
2	Power connector	5	SD Card Reader
3	Thunderbolt™ 5 with USB Type-C® 80Gbps signaling rate (USB Power Delivery, DisplayPort™ 2.1)*		

*Actual throughput may vary.

Features

PRODUCT NAME

HP ZBook Fury G1i 18 inch Mobile Workstation PC

OPERATING SYSTEM

Preinstalled OS

FreeDOS
Ubuntu Linux 24.04
Windows 11 Pro¹

Windows 11 Home - HP recommends Windows 11 Pro for business¹
Windows 11 Home Single Language - HP recommends Windows 11 Pro for business¹
Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement)¹

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>. A full list of HP products and the Windows 10 versions tested is available on the HP support website. <https://support.hp.com/us-en/document/c05195282>

PROCESSOR

Intel® Core™ Ultra 9 Processor 285HX with Intel® Graphics and Intel® AI Boost (13 NPU TOPS), (2.1 GHz E-core base frequency, 2.8 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.5 GHz P-core Max Turbo frequency, 36MB Cache, 8 P-cores and 16 E-cores, 24 threads), supports Intel vPro® Enterprise

Intel® Core™ Ultra 7 Processor 265HX with Intel® Graphics and Intel® AI Boost (13 NPU TOPS), (2.3 GHz E-core base frequency, 2.6 GHz P-core base frequency, up to 4.6 GHz E-core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 30MB Cache, 8 P-cores and 12 E-cores, 20 threads), supports Intel vPro® Enterprise

Intel® Core™ Ultra 7 Processor 255HX with Intel® Graphics and Intel® AI Boost (13 NPU TOPS), (1.8 GHz E-core base frequency, 2.4 GHz P-core base frequency, up to 4.5 GHz E-core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 30MB Cache, 8 P-cores and 12 E-cores, 20 threads)

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.



Features

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See <http://intel.com/vpro>

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

⁵ Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

⁶ Features and software that require a NPU may require software purchase, subscription or enablement by a software or platform provider, and third-party software may have specific configuration or compatibility requirements. Performance varies by use, configuration, and other factors.

CHIPSET

Intel® WM890

GRAPHICS

Integrated

Intel® Graphics

Discrete

NVIDIA RTX PRO 5000 Blackwell Generation Laptop GPU (24 GB GDDR7 dedicated);
NVIDIA RTX PRO 4000 Blackwell Generation Laptop GPU (16 GB GDDR7 dedicated);
NVIDIA RTX PRO 3000 Blackwell Generation Laptop GPU (12 GB GDDR7 dedicated);
NVIDIA RTX PRO 2000 Blackwell Generation Laptop GPU (8 GB GDDR7 dedicated);
NVIDIA RTX PRO 1000 Blackwell Generation Laptop GPU (8 GB GDDR7 dedicated);

Supports

RTX PRO 5000 / RTX PRO 4000 / RTX PRO 3000 Support Memory ECC

DP 2.1, HDMI 2.1b

Supports CUDA, Dynamic Boost



Features

DISPLAY

Non-Touch

45.7 cm (18") diagonal, WQXGA (2560 x 1600), anti-glare, UWVA, LED, 500 nits, eDP 1.4 + PSR2, 165Hz, flat LCD Panel, 100% DCI-P3

Displays support

Supports up to 4 displays through the HP Thunderbolt 280W G4 Dock

Display Size

18.0"

45.7 cm (18")

DOCKING (Sold Separately)

Docking station model #1

Total number of supported displays (incl.the
notebook)
display)

Max.resolutions supported

Dock Connectors

HP Quick Connect Support

Extended Power Range Support

Technical limitations

Thunderbolt Hosts

Non-Thunderbolt hosts

Docking station model #2

HP Thunderbolt 4 Ultra 180W G6 Dock

4

(4) 4K @60Hz*
(2) 4K @ 120Hz*
(3) QHD @ 120Hz*
(1) QHD @ 360Hz*

1x HDMI 2.1, 2x DisplayPort 1.4, 1x Thunderbolt 4, 1x USB-C 3.2 Gen 2 DisplayPort

Yes

Yes

Requires DisplayPort 1.4 support with Display Stream Compression (DSC).
Bluetooth required for HP Quick Connect. HP Quick Connect available on select HP
notebooks.

Maximum resolution and display support is dependent on the maximum capability
of the notebook.

Maximum of (4) displays with maximum resolution of 5K@ 30Hz running
Thunderbolt host.

Maximum resolution possible is dual 8K displays @ 60Hz running Thunderbolt host
or running a non-Thunderbolt host in high resolution mode @30Hz

The highest resolution for dual displays running a non-Thunderbolt host in multi-
function mode is

(1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port

Non-Thunderbolt hosts support (3) displays with a maximum resolution of (2) 5K
single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode
the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD
@ 30Hz.

HP Thunderbolt™ 120W G4 Dock



Features

Total number of supported displays (incl.the notebook display)	4
Max.resolutions supported	Quad 4K @60Hz Dual 8K single cable@30 for Thunderbolt hosts or USB-C hosts DisplayPort 1.4 with Display Stream Compression in High-Resolution Mode
Dock Connectors	2x HDMI 2.0, 2x DisplayPort 1.4, 1x Thunderbolt 4, 1x USB-C 3.2 Gen 2 DisplayPort
Technical limitations	Maximum resolution and display support is dependent on the maximum capability of the notebook. Thunderbolt Hosts: Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host. Maximum resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in high resolution mode @30Hz Non-Thunderbolt hosts: The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port Non-Thunderbolt hosts support (3) displays with a maximum resolution of (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.

Features

STORAGE AND DRIVES

Primary M.2 Storage

4 TB PCIe® Gen4x4 NVMe™ M.2 SSD TLC

2 TB PCIe® Gen4x4 NVMe™ M.2 SSD TLC

2 TB PCIe® Gen4x4 NVMe™ SED SSD

1 TB PCIe® Gen4x4 NVMe™ M.2 SSD TLC

1 TB PCIe® Gen4x4 NVMe™ SED SSD

512 GB PCIe® Gen4x4 NVMe™ M.2 SSD TLC

512 GB PCIe® Gen4x4 NVMe™ SED SSD

2 TB Citadel PCIe-3x4 NVMe™ M.2 2280 TLC SED OPAL2 FIPS SSD

1 TB Citadel PCIe-3x4 NVMe™ M.2 2280 TLC SED OPAL2 FIPS SSD

512GB Citadel PCIe-3x4 NVMe™ M.2 2280 TLC SED OPAL2 FIPS SSD

Features

MEMORY

Maximum Memory

128 GB DDR5-5600 MT/s ECC;
192 GB DDR5-5600 MT/s non-ECC
256 GB DDR5-6400 MT/s non-ECC*

Memory

24GB (1x24GB) DDR5 5600 SODIMM Memory

48GB (2x24GB) DDR5 5600 SODIMM Memory

128GB (4x32GB) DDR5 5600 SODIMM Memory

16GB (1x16GB) DDR5 5600 SODIMM Memory

32GB (1x32GB) DDR5 5600 SODIMM Memory

32GB (2x16GB) DDR5 5600 SODIMM Memory

64GB (2x32GB) DDR5 5600 SODIMM Memory

64GB (4x16GB) DDR5 5600 SODIMM Memory

32GB (1x32GB) DDR5 6400 CSODIMM Memory

64GB (1x64GB) DDR5 6400 CSODIMM Memory

64GB (2x32GB) DDR5 6400 CSODIMM Memory

128GB (2x64GB) DDR5 6400 CSODIMM Memory

256GB (4x64GB) DDR5 6400 CSODIMM Memory

16GB (1x16GB) DDR5 5600 SODIMM ECC Memory

32GB (2x16GB) DDR5 5600 SODIMM ECC Memory

32GB (1x32GB) DDR5 5600 SODIMM ECC Memory

64GB (2x32GB) DDR5 5600 SODIMM ECC Memory

128GB (4x32GB) DDR5 5600 SODIMM ECC Memory

Memory Speed

Memory DDR5 6400 CSODIMM

Memory DDR5 5600 SODIMM

Intel 15th Gen Core HX-Series Processors: Memory transfer speed will be 4000 MT/s or 4400 MT/s under identical DIMM conditions

Current identical DIMM conditions:

- 2 DIMM Per channel (with 2 Rank DDR5 module): 4000 MT/s
- 2 DIMM Per channel (with 1 Rank DDR5 module): 4400 MT/s
- 1 DIMM per channel (with either 1 Rank or 2 Rank DDR module): 4400 MT/s

Note: DIMM per Channel is DPC

Note: 16GB DIMM is 1 Rank module

Note: 32GB and 64GB DIMM are 2 Rank module



Features

DIMM1	DIMM2	DIMM3	DIMM4	MEM Speed	DIMM/Channel
V				1 Rank: 4400 MT/s 2 Rank: 4400 MT/s	1 DPC
V	V			1 Rank: 4400 MT/s 2 Rank: 4400 MT/s	1 DPC
V	V	V		1 Rank: 4400 MT/s 2 Rank: 4400 MT/s	2 DPC
V	V	V	V	1 Rank: 4400 MT/s 2 Rank: 4400 MT/s	2 DPC

Mixing Memory DIMM Vendors/Suppliers

Mixing memory DIMM suppliers and / or capacity may cause a downgrade in memory speed, signal integrity or functional issues

Mixing memory Rank (1 Rank and 2 Rank from table above) in the same channel will cause the memory speed to drop to 3200 MHz and could encounter an unstable condition

Recommendation: Do not install different Rank memory modules in the same channel

Memory Installation Sequence

Intel 15th Gen Core HX-Series Processors have specific population (installation sequence) rules. To Avoid a no-boot issue.

There is/are DIMM population installation sequence requirements for cases where only one DIMM is populated per channel.

Then the furthest memory connectors from the CPU should be populated first

*256 GB DDR5-6400 MT/s non-ECC will be available 2nd Half 2025

Note: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Features

NETWORKING /COMMUNICATIONS

WLAN

Intel® Wi-Fi 7 BE200 (2x2) and Bluetooth® 5.4 WLAN, vPro®^{1,2}

Intel® Wi-Fi 7 BE200 (2x2) and Bluetooth® 5.4 WLAN, non-vPro®^{1,2}

WWAN

HP R15 5G Solution WWAN³

WLPWAN

Qualcomm 9205 LTE-M (CAT-M1 fSVC)⁴

NFC

WNC XRAV-1 NFC

Ethernet

Intel I226-LM 2.5GbE Ethernet Controller

Intel I226-V 2.5GbE Ethernet Controller

¹Wi-Fi 7: Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires compatible Windows 11 OS, compatible processor, and separately purchased Wi-Fi 7 router to support backwards compatibility with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported. The specification for 802.11BE is a draft specification and is not final. If the final specification differs from the draft specification, it may affect the ability of the device to communicate with other 802.11BE devices.

²Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See <http://intel.com/vpro>

³5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (EN-DC) with both 100MHz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

⁴LPWAN (also called Mobile Narrowband) support HP Protect & Trace with Wolf Connect service through the subscription term, but do not support mobile broadband use.



Features

AUDIO/MULTIMEDIA

Audio

Audio by Poly Studio,
4 integrated stereo speakers; discrete amplifiers
2 integrated dual array digital microphones

Speaker Power

(1W/8 ohm per speaker),

Camera

5MP Camera; IR Camera (optional)

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard – spill-resistant, full-size, backlit keyboard and DuraKeys

HP Lumen RGB Z Keyboard – Full-size, per-key RGB backlit keyboard

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default

Function Keys

ESC: system information

F1 - Display Switching

F2 - Night Mode / Sure View LED: On = White; Off = Not illuminated

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute LED: On = Amber; Off = not illuminated

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute On = Amber; Off = not illuminated

F9 - Keyboard Backlight

F10 - Insert

F11 - Airplane Mode

F12 - Command center

> Print Screen

> Power On/Off On = White; Off = not illuminated

> Delete

> Fn key lock

> Microsoft Copilot¹

Hidden Keys

home

end

Fn+R = Break

Fn+S = Sys Rq

Fn+C = Scroll Lock

Fn+W = Pause

¹Copilot in Windows requires Windows 11. Some features require an NPU. Timing of feature delivery and availability varies by market and device. Requires Microsoft account to log in. Where Microsoft in Windows is not available, the Copilot key will lead to the Bing search engine. Use of Recall requires customer authentication using Windows Hello Enhanced Sign in Security (ESS) which requires a fingerprint reader or facial recognition camera and may not be supported on all platforms. See <http://aka.ms/WindowsAIFeatures>

Features

SOFTWARE AND SECURITY

Software

Buy Microsoft Office (Sold Separately)

CoPilot in Windows with CoPilot Key¹

Edge Customization

HP Connection Optimizer

HP Hotkey Support

HP Mac Address Manager

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Privacy Settings

HP Services Scan²

HP Smart Support³

HP Support Assistant⁴

HSA Fusion for Commercial

HSA Telemetry for Commercial

myHP⁵

Poly Camera Pro

Poly Lens⁶

Manageability Features

HP Client Catalog (download)⁷

HP Client Management Script Library (download)⁸

HP Cloud Recovery⁹

HP Connect for Microsoft Endpoint Manager¹⁰

HP Driver Packs (download)¹¹

HP Image Assistant (download)¹²

HP Manageability Integration Kit (download)¹³

HP Power Manager with Battery Health Manager (download)¹⁴

Security Management

Secured-Core PC Enable¹⁵

Windows Hello Enhanced Sign-In Security (ESS)

HP Wolf Security for Business which includes:¹⁶

HP Sure Admin¹⁷

HP Sure Click¹⁸

HP Sure Recover¹⁹

HP Sure Run²⁰

HP Sure Sense²¹

HP Sure Start²²



Features

HP Tamper Lock²³

BIOS

Absolute Persistence Module²⁴

Audio Permanent Disable

BIOS Update via Network

HP BIOS Recovery

HP BIOSphere²⁵

HP DriveLock & Automatic DriveLock

HP Fingerprint Sensor²⁶

HP Secure Erase²⁷

HP Wake on WLAN

UEFI version: v2.9

Security

TPM

Model: Nuvoton NPCT760HACYX

FIPS 140-2 Compliant: Yes

Model: STMicroelectronics ST33KTPM2X32CKE2

FIPS 140-2 Compliant: Yes

1. Copilot key is available on select Windows 11 PCs. Where Microsoft Copilot is not available, the Copilot key will lead to the Bing search engine. Copilot key feature availability varies by market, see aka.ms/keysupport. Copilot is NOT available in China, Russia, Belarus, and embargoed regions Cuba, Iran, North Korea, Crimea.

2. HP Services Scan is preinstalled and/or provided thru Windows Update and checks for service entitlement on each hardware device and downloads the applicable software agent automatically. To disable this feature, please follow the instructions at <http://www.hpdaas.com/requirements>. The HP Insights agent is a telemetry and analytics platform that provides critical data around devices and applications and is not sold as a standalone service. HP follows stringent GDPR privacy regulations and is ISO27001, ISO27701, ISO27017 and SOC2 Type2 certified for Information Security. Internet access with connection to the HP Insights agent is required. For full system requirements, please visit <http://www.hpdaas.com/requirements>. Not available in China.

3. HP Smart Support requires the HP Insights agent to be installed. For more information about how to enable or to download HP Smart Support, please visit <http://www.hp.com/smart-support>. HP Services Scan is preinstalled and/or provided thru Windows Update and will check entitlement on each hardware device to determine if an HP Insights agent-enabled service has been purchased, and will download applicable software automatically. HP Insights agent is a telemetry and analytics platform that provides critical data around devices and applications and is not sold as a standalone service. HP follows stringent GDPR privacy regulations and is ISO27001, ISO27701, ISO27017 and SOC2 Type2 certified for Information Security. Internet access is required. For full system requirements or to disable this feature, please visit <https://www.hpdaas.com/requirements>.

4. HP Support Assistant is available on Windows. For more information, please visit <http://www.support.hp.com/help/hp-support-assistant>.

5. MyHP requires Windows 10 or higher OS.

6. Poly Lens Desktop requires a Windows OS.

7. HP Client Catalog not preinstalled, however available for download at (<https://www.hp.com/us-en/solutions/client-management>



Features

[solutions.html](#)

8. HP Client Management Script Library (<https://www.hp.com/us-en/solutions/client-management-solutions.html#tab=manageability-tools>).

9. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/computer>.

10. HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.

11. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

12. HP Image Assistant not preinstalled, however available for download at (<https://ftp.ext.hp.com/pub/caps-softpaq/cmit/HPIA.html>),

13. HP Manageability Integration Kit not presintalled, however available for downloaded from <https://www.hp.com/us-en/solutions/client-management-solutions.html#tab=manageability-tools>.

14. HP Power Manager with Battery Health can be downloaded by entering your system information here: https://support.hp.com/in-en/document/ish_4449597-3519507-16.

15. Secured-Core PC Enable requires an Intel® vPro®, AMD Ryzen™ Pro processor or Qualcomm® processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC is enabled from the factory.

16. HP Wolf Security for Business requires Windows 10 or 11 Pro or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features.

17. HP Sure Admin requires HP G8 or newer platforms, Windows 10 or higher, HP BIOS, HP Manageability Kit or KMS Service from <http://www.hp.com/go/clientmanagement> and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

18. HP Sure Click requires Windows 10 and higher. See https://bit.ly/2PrLT6A_SureClick for complete details.

19. HP Sure Recover is available on select HP PCs and requires Windows 10 or 11 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover Gen6 with Embedded Reimaging is an optional feature on select HP PCs which requires Windows 10 or 11 must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.

20. HP Sure Run is available on select HP PCs and requires Windows 10 and higher.

21. HP Sure Sense requires Windows 10 and higher. See product specifications for availability. On units with WWAN shipping to China, HP Sure Sense is only available via Softpaq download.

22. HP Sure Start is available on select HP PCs and requires Windows 10 and higher.

23. HP Tamper Lock must be enabled by the customer or your administrator.

24. Absolute Persistence firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: <https://www.absolute.com/about/legal/agreements/absolute/>.

25. HP BIOSphere features may vary depending on the platform and configuration.

26. HP Fingerprint Reader is an optional feature that requires Windows 10 or 11 and must be configured at purchase.

27. HP Secure Erase implements the methods outlined in the National Institute of Standards and Technology Special Publication 800-88r "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.



Features

POWER

Power Supply¹⁶

HP 200W Slim 4.5 mm PFC Right Angle Smart (3-pin) AC Power Adapter;
HP 280W Slim 4.5 mm PFC Right Angle Smart (3-pin) AC Power Adapter;
HP 330W Slim 4.5 mm PFC Right Angle Smart (3-pin) AC Power Adapter;
Not Included AC Adapter

Battery

HP 99 Wh Long Life Polymer Fast Charge 8 cell Battery

Power Cord

C13 1.83m Paper Sticker Flange Premium CWP Black Straight Halogen Free Power Cord
C13 1.83m Paper Sticker Flange Premium CWP Black Straight Power Cord
Not Included Power Cord

Battery life

Discrete
Up to 8:37 hrs



Features

WEIGHT & DIMENSIONS

Weight¹

Starting at 7.78 lb

(Weight varies by configuration and components.)

Starting at 3.52 kg;

(Weight varies by configuration and components.)

Product Dimensions (w x d x h)

15.88 x 11.41 x 1.10 in

(Dimensions vary by configuration)

40.3 x 28.9 x 2.7 cm

(Dimensions vary by configuration)

Features

PORTS/SLOTS

Left Side

1 power connector
2 Thunderbolt™ 5 with USB Type-C® 80 Gbps signaling rate (USB Power Delivery, DisplayPort™ 2.1)*
1 HDMI 2.1
SD 7.0 Media Card Reader

Right side:

1 Thunderbolt™ 4 with USB Type-C® 40 Gbps signaling rate (USB Power Delivery, DisplayPort™ 2.1)*
1 USB Type-A 10Gbps signaling rate
1 headphone/microphone combo
1 RJ-45
1 nano security lock slot
1 smart card reader

Expansion Slots

SD 7.0 Media Card Reader

[*Actual throughout may vary.](#)

Features

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. HP Worldwide Limited Warranty for the battery is aligned with the warranty period of the HP Hardware Product. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.

Certification and Compliance

ENERGY STAR® certified

EPEAT® registered configurations available

Low halogen

Sustainable Impact Specifications

40% post-consumer recycled plastic

Bulk packaging available

External power supply 90% efficiency;

Molded paper pulp cushion inside box is 100% sustainably sourced and recyclable;

Outside box and corrugated cushions are 100% sustainably sourced and recyclable

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage 19.5V

Average Operating Power

Integrated graphics CPU < 55W

Discrete Graphics

NVIDIA RTX PRO 5000 Blackwell 135W

NVIDIA RTX PRO 4000 Blackwell 135W

NVIDIA RTX PRO 3000 Blackwell 115W

NVIDIA RTX PRO 2000 Blackwell 60W

NVIDIA RTX PRO 1000 Blackwell 60W

<330W

Max Operating Power

Temperature

Operating

32° to 95° F (0° to 35° C), System performance may be reduced above 32°C (89.6°F).

No sustained direct exposure to sunlight.

-4-140°F (-20 - 60°C)

Non-operating

Relative Humidity

Operating

10% to 90%, non-condensing

Non-operating

5% to 95%; 38.7C (101.6F) maximum wet bulb temperature; non-condensing.

Shock

Operating

40 G, 2 ms, half-sine

Non-operating

240G, 2ms, half sine

Random Vibration

Operating

0.079 ~ 1.043 grams

Non-operating

3.5 grams

Altitude (unpressurized)

Operating

3048m (10,000ft)

Non-operating

12192m (40,000ft)

Planned Industry Standard Certifications

Regulatory Model Number

HSN-I64C-8

UL

Yes

CSA

Yes

FCC Compliance

Yes

ENERGY STAR®

Yes

EPEAT

Gold

ICES

Yes

Australia /

Yes

NZ A-Tick Compliance

Yes

CCC

Yes

Japan VCCI Compliance

Yes

KC

Yes

BSMI

Yes

CE Marking Compliance

Yes

BNCI or BELUS

No



Technical Specifications – System Unit

CIT	
EAC	Yes
SASO	Yes
SABS	Yes
UKRSERTCOMPUTER	

Technical Specifications – Displays

DISPLAYS

Actual brightness will be lower with touchscreen or HP Sure View.

Availability may vary by country

18.0 in WQXGA (2560 x 1600)

Anti-Glare UWVA LED DCI-P3

100 500 eDP 1.4+PSR2

165Hzflat LCD Panel

Outline Dimensions (W x H)	394.56 x 264.80 (max)
Active Area	387.76 x 242.35 (typ)
Weight	560 (max)
Diagonal Size	18
Thickness	3.32/3.5 (max)
Interface	eDP 1.4
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ)
Refresh Rate	165Hz (typ)
Brightness	500 (typ)
Pixel Resolution - Format	2560 x 1600 (WQXGA)
Backlight	WLED
Pixel Resolution	RGB
Color Gamut Coverage	DCI P3 100%
Color Depth	8
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	Yes
Power Consumption (W, EBL@ 150nits max/ 200nits max)	4.18 (max)/4.97(max)

Technical Specifications – Storage

STORAGE

SSD 512GB 2280 PCIe-4x4 NVMe Three Layer Cell

Form Factor	M.2 2280
Capacity	512GB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	3500 MB/s ±20%
Logical Blocks	1000215215
Features	Pyrite 2.0; TRIM; L1.2

SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell

Form Factor	M.2 2280
Capacity	1TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	5000 MB/s ±20%
Logical Blocks	2000409264
Features	Pyrite 2.0; TRIM; L1.2

1TB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive

Form Factor	M.2 2280
Capacity	1TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	5000 MB/s ±20%
Logical Blocks	2000409264
Features	Pyrite 2.0; TRIM; L1.2

1TB PCIe-5x4 2280 NVMe Solid State Drive

Form Factor	M.2 2280
Capacity	1TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen5X4
Sequential Read	13000 MB/s ±20%
Sequential Write	9000 MB/s ±20%
Logical Blocks	



Technical Specifications – Storage

Features	Pyrite 2.0; TRIM; L1.2
2TB PCIe-4x4 2280 NVMe Three Layer Cell Solid State Drive	
Form Factor	M.2 2280
Capacity	2TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	5000 MB/s ±20%
Logical Blocks	4000797360
Features	Pyrite 2.0; TRIM; L1.2
2TB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive	
Form Factor	M.2 2280
Capacity	2TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	5000 MB/s ±20%
Logical Blocks	4000797360
Features	Pyrite 2.0; TRIM; L1.2
2TB PCIe-5x4 2280 NVMe Solid State Drive	
Form Factor	M.2 2280
Capacity	2TB
NAND Type	TLC
Weight	10 g (0.02 lb)
Interface	PCIe NVMe Gen5X4
Sequential Read	13500 MB/s ±20%
Sequential Write	10000 MB/s ±20%
Logical Blocks	
Features	Pyrite 2.0; TRIM; L1.2
4TB PCIe-4x4 2280 NVMe Three Layer Cell double-sided M.2 Solid State Drive	
Form Factor	M.2 2280
Capacity	4TB
NAND Type	TLC
Weight	15 g
Interface	PCIe NVMe Gen4X4
Sequential Read	6400 MB/s ±20%
Sequential Write	5000 MB/s ±20%

Technical Specifications – Storage

Logical Blocks	8001573552
Features	Pyrite 2.0; TRIM; L1.2

Technical Specifications – Networking

NETWORKING / COMMUNICATION

Intel BE200 Wi-Fi 7 +Bluetooth® 5.4 M.2 320MHz PCIe World-wide WLAN vPro¹

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11be IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax/be 2.402 – 2.482 GHz 802.11a/n/ac/ax/be 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz 5.955 – 6.415 GHz 6.435 – 6.515 GHz 6.535 – 6.875 GHz 6.895 – 7.115 GHz
Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac: 1733Mbps 802.11ax: max 2.4Gbps 802.11be: max 5.76Gbps
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM, 4096QAM

Technical Specifications – Networking

Security³	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
Roaming	Infrastructure (Access Point Required)
Output Power²	IEEE 802.11 compliant roaming between access points 802.11b, 1Mbps: +17dBm minimum 802.11g, 6Mbps: +16dBm minimum 802.11a, 6Mbps: +17dBm minimum 802.11n, MCS7(HT20): +14dBm minimum 802.11n, MCS7(HT40): +13.5dBm minimum 802.11ac MCS9(VHT20): 13.5dBm minimum 802.11ac MCS9(VHT40): +13.5dBm minimum 802.11ac MCS9(VHT80): +12.5dBm minimum 802.11ac MCS9(VHT160): +10.5dBm minimum 802.11ax MCS11(HE20)(6GHz): +11.5dBm minimum 802.11ax MCS11(HE40)(6GHz): +7.5dBm minimum 802.11ax MCS11(HE80)(6GHz): +7.5dBm minimum 802.11ax MCS11(HE160)(6GHz): +7.5dBm minimum 802.11be MCS13(EHT20)(6GHz): 11.5dBm 802.11be MCS13(EHT40)(6GHz): 7.5dBm 802.11be MCS13(EHT80)(6GHz): 7.5dBm 802.11be MCS13(EHT160)(6GHz): 6.5dBm 802.11be MCS13(EHT320)(6GHz): 4.5dBm
Power Consumption	Transmit mode 3.1 W Receive mode 1.8 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -85dBm maximum 802.11a/g, 6Mbps: -90.5dBm maximum 802.11a/g, 54Mbps: -72.5dBm maximum



Technical Specifications – Networking

Antenna type	802.11n, MCS0(HT20): -90dBm maximum 802.11n, MCS7(HT20): -71.5dBm maximum 802.11n, MCS0(HT40): -88.5dBm maximum 802.11n, MCS7(HT40): -68.5dBm maximum 802.11ac, MCS9(VHT20): -88.5dBm maximum 802.11ac, MCS9(VHT40): -65.5dBm maximum 802.11ac, MCS9(VHT80): -60.5dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum 802.11ax, MCS11(HE20)(6GHz): -59.5dBm maximum 802.11ax, MCS11(HE40)(6GHz): -56.5dBm maximum 802.11ax, MCS11(HE80)(6GHz): -53.5dBm maximum 802.11ax, MCS11(HE160)(6GHz): -51.5dBm maximum 802.11be, MCS13(EHT20)(6GHz): -55.5dBm maximum 802.11be, MCS13(EHT40)(6GHz): -53.5dBm maximum 802.11be, MCS13(EHT80)(6GHz): -51.5dBm maximum 802.11be, MCS13(EHT160)(6GHz): -48.5dBm maximum 802.11be, MCS13(EHT320)(6GHz): -45.5dBm maximum
Form Factor	High efficiency antenna with spatial diversity
Dimensions	Two embedded tri-band 2.4/5/6 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Weight	PCI-Express M.2 MiniCard
	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Operating Voltage	1. Type 2230: 2.8g
Temperature	2. Type 1216: 1.3g
	3.3v +/- 9%
Humidity	Operating: 14° to 158° F (-10° to 70° C)
Altitude	Non-operating: -40° to 176° F (-40° to 80° C)
LED Activity	Operating: 10% to 90% (non-condensing)
Subtitle	Non-operating: 5% to 95% (non-condensing)
Bluetooth Specification	Operating: 0 to 10,000 ft (3,048 m)
Frequency Band	Non-operating: 0 to 50,000 ft (15,240 m)
Number of Available Channels	LED Amber – Radio OFF; LED OFF – Radio ON
Data Rates and Throughput	HP Integrated Module with Bluetooth
	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Technology
	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Compliant
	2402 to 2480 MHz
	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3,64 kbps, voice channels

Technical Specifications – Networking

Transmit Power	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class I Bluetooth device with a maximum transmit power of +15.5 dBm for BR and +13dBm for EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW
Bluetooth Software Supported	Selective Suspend: 17 mW
Link Topology	1. Microsoft Windows Bluetooth Software 2. Linux/Chrome OS Bluetooth Software.
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Certifications	FCC (47 CFR) Part 15C/E, Section 15.247, 15.249, 15.407
Bluetooth Profiles Supported	ETSI 300 328, ETSI 301 893, ETSI 303 687 Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Bluetooth 5.3

Technical Specifications – Networking

Host to Controller Encryption Key Control Enhancements
Compliance to the latest Errata Section 12.3 of BT 5.3 specification

1. Wi-Fi 7 requires a Wi-Fi 7 router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 7 is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 7 is supported. Wi-Fi 7 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
2. Check latest software/driver release for updates on supported security features.
3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel BE200 Wi-Fi 7 + Bluetooth® 5.4 M.2 320MHz PCIe World-wide WLAN non-vPro¹

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11be IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax/be 2.402 – 2.482 GHz 802.11a/n/ac/ax/be 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz 5.955 – 6.415 GHz 6.435 – 6.515 GHz 6.535 – 6.875 GHz 6.895 – 7.115 GHz
Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps



Technical Specifications – Networking

Modulation	802.11ac: 1733Mbps 802.11ax: max 2.4Gbps 802.11be: max 5.76Gbps Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM, 4096QAM
Security³	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI Ad-hoc (Peer to Peer)
Network Architecture Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	802.11b, 1Mbps: +17dBm minimum 802.11g, 6Mbps: +16dBm minimum 802.11a, 6Mbps: +17dBm minimum 802.11n, MCS7(HT20): +14dBm minimum 802.11n, MCS7(HT40): +13.5dBm minimum 802.11ac MCS9(VHT20): 13.5dBm minimum 802.11ac MCS9(VHT40): +13.5dBm minimum 802.11ac MCS9(VHT80): +12.5dBm minimum 802.11ac MCS9(VHT160): +10.5dBm minimum 802.11ax MCS11(HE20)(6GHz): +11.5dBm minimum 802.11ax MCS11(HE40)(6GHz): +7.5dBm minimum 802.11ax MCS11(HE80)(6GHz): +7.5dBm minimum 802.11ax MCS11(HE160)(6GHz): +7.5dBm minimum 802.11be MCS13(EHT20)(6GHz): 11.5dBm 802.11be MCS13(EHT40)(6GHz): 7.5dBm 802.11be MCS13(EHT80)(6GHz): 7.5dBm 802.11be MCS13(EHT160)(6GHz): 6.5dBm 802.11be MCS13(EHT320)(6GHz): 4.5dBm
Power Consumption	Transmit mode 3.1 W Receive mode 1.8 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW

Technical Specifications – Networking

Power Management	ACPI and PCI Express compliant power management
Receiver Sensitivity³	802.11 compliant power saving mode 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -85dBm maximum 802.11a/g, 6Mbps: -90.5dBm maximum 802.11a/g, 54Mbps: -72.5dBm maximum 802.11n, MCS0(HT20): -90dBm maximum 802.11n, MCS7(HT20): -71.5dBm maximum 802.11n, MCS0(HT40): -88.5dBm maximum 802.11n, MCS7(HT40): -68.5dBm maximum 802.11ac, MCS9(VHT20): -88.5dBm maximum 802.11ac, MCS9(VHT40): -65.5dBm maximum 802.11ac, MCS9(VHT80): -60.5dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum 802.11ax, MCS11(HE20)(6GHz): -59.5dBm maximum 802.11ax, MCS11(HE40)(6GHz): -56.5dBm maximum 802.11ax, MCS11(HE80)(6GHz): -53.5dBm maximum 802.11ax, MCS11(HE160)(6GHz): -51.5dBm maximum 802.11be, MCS13(EHT20)(6GHz): -55.5dBm maximum 802.11be, MCS13(EHT40)(6GHz): -53.5dBm maximum 802.11be, MCS13(EHT80)(6GHz): -51.5dBm maximum 802.11be, MCS13(EHT160)(6GHz): -48.5dBm maximum 802.11be, MCS13(EHT320)(6GHz): -45.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity Two embedded tri-band 2.4/5/6 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
Subtitle	HP Integrated Module with Bluetooth
Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Technology 4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Compliant



Technical Specifications – Networking

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class I Bluetooth device with a maximum transmit power of +15.5 dBm for BR and +13dBm for EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	1. Microsoft Windows Bluetooth Software 2. Linux/Chrome OS Bluetooth Software.
Link Topology	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Certifications	FCC (47 CFR) Part 15C/E, Section 15.247, 15.249, 15.407
Bluetooth Profiles Supported	ETSI 300 328, ETSI 301 893, ETSI 303 687 BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions



Technical Specifications – Networking

Channel Selection Algo
Limited High Duty Cycle Non-Connectable Advertising
2Mbps LE
LE Long Range
BT5.3
Host to Controller Encryption Key Control Enhancements
Compliance to the latest Errata Section 12.3 of BT 5.3 specification

1. Wi-Fi 7 requires a Wi-Fi 7 router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 7 is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 7 is supported. Wi-Fi 7 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP 5G Sub-6 Cat 19

Technology/Operating bands
WCDMA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)



Technical Specifications – Networking

Band 32: 1452 to 1496 MHz (DL)
Band 34: 2010 to 2025 MHz (UL/DL)
Band 38: 2570 to 2620 MHz (UL/DL)
Band 39: 1880 to 1920 MHz (UL/DL)
Band 40: 2300 to 2400 MHz (UL/DL)
Band 41: 2496 to 2690 MHz (UL/DL)
Band 42: 3400 to 3600 MHz (UL/DL)
Band 43: 3400 to 3800 MHz (UL/DL)
Band 46: 5150 to 5925 MHz (DL)
Band 48: 3550 to 3700 MHz (UL/DL)
Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)
Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)
5GNR Sub 6GHz
n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
n25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)
n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
n30: 2305 to 2315 MHz (UL), 2350 to 2360 MHz (DL)
n38: 2570 to 2620 MHz (UL/DL)
n40: 2300 to 2400 MHz (UL/DL)
n41: 2496 to 2690 MHz (UL/DL)
n48: 3550 to 3700 MHz (UL/DL)
n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)
n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)
n77: 3300 to 4200 MHz (UL/DL)
n78: 3300 to 3800 MHz (UL/DL)
n79: 4400 to 5000 MHz (UL/DL)

Wireless protocol standards

NR Sub6G Rel15
200MHz 2 DLCA, 256 QAM
200MHz 2 ULCA, 256 QAM
15KHz/30KHz SCS for FDD/TDD

LTE Rel15
100MHz 5 DLCA, 256 QAM
40MHz 2 ULCA, 256 QAM
UMTS Rel8

GPS

GPS only support L1 C/A



Technical Specifications – Networking

GPS bands	GPS: L1 (1575.42MHz) GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)
Maximum data rates	Sub-6 SA Peak DL 4.67Gbps/UL 1.25Gbps Sub-6 NSA Peak DL 3.74Gbps/UL 835Mbps LTE Peak DL 1.6Gbps (CAT19)/UL 211Mbps (CAT18) UMTS/HSPA+ DL DC-HSPA+: 42 Mbps (CAT24)/UL 11.5 Mbps (CAT7)
Maximum output power	NR : 23 dBm in all band except (n30 = 22dBm & n48=21dBm & n77=25dBm & n41/n77/n78 = 26dBm) LTE: 23 dBm in all band except (B30 = 22dBm & B48=21dBm & B41=26dBm) UMTS: 23.5 dBm
Maximum power consumption	3500 mA (peak); 1674mA (average)
Form Factor	M.2, 3052-S3 Key B
Weight	8.7g
Dimensions	52 mm x 30 mm x 2.3 mm
(Length x Width x Thickness)	
embedded eSIM	Support

1. 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

Qualcomm 9205

Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 800 (Band 27), 700 (Band 28), 1700/2100 (Band 66), 700 (band 85) MHz. GSM/GPRS/EGPRS: 850, 900, 1800, 1900MHz.
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Technical Specifications – Networking

Wireless protocol standards	I 3GPP TS 51.010-1 V10.5.0: Mobile Station (MS) conformance specification; Part 1: Conformance specification I 3GPP TS 36.521-1 V14.3.0: User Equipment (UE) conformance specification; Radio transmission and reception; Part 1: Conformance testing I 3GPP TS 21.111 V10.0.0: USIM and IC card requirements I 3GPP TS 51.011 V4.15.0: Specification of the Subscriber Identity Module -Mobile Equipment (SIM-ME) interface I 3GPP TS 31.102 V10.11.0: Characteristics of the Universal Subscriber Identity Module (USIM) application I 3GPP TS 31.11 V10.16.0: Universal Subscriber Identity Module (USIM) Application Toolkit (USAT) I 3GPP TS 36.124 V10.3.0: Electro Magnetic Compatibility (EMC) requirements for mobile terminals and ancillary equipment I 3GPP TS 27.007 V10.0.8: AT command set for User Equipment (UE) I 3GPP TS 27.005 V10.0.1: Use of Data Terminal Equipment - Data Circuit terminating Equipment (DTE - DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS) Standalone GPS/Beidou/Glonass, A-GPS(XTRA)
GPS	
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
Maximum data rates	LTE FDD: 375 Kbps (Download), 1119 Kbps (Upload) GSM: - GPRS: 107 Kbps (Download), 85.6 Kbps (Upload) - EGPRS: 296 Kbps (Download), 236.8 Kbps (Upload)
Maximum output power	LTE: 21.5 dBm in all band GSM:34dBm
Maximum power consumption	LTE: 147 mA(peak), 18 mA(average)
Form Factor	M.2
Weight	4 g
Dimensions (Length x Width x Thickness)	22 x 42 x 2.3 mm
embedded eSIM	Support
NFC NXP NPC300	Dimensions (L x W x H) 17 x 10 x 2.0 mm Chipset NPC300 System interface I2C NFC RF standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092



Technical Specifications – Networking

NFC Forum Support Reader (PCD-VCD) Mode(1)	ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2 Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
Frequency	13.56 MHz
NFC Modes Supported	Reader/Writer, Peer-to-Peer
Raw RF Data Rates	106, 212, 424, 848 kbps
Operating temperature	Operating: 0 °C to 70 °C (32 °F to 158 °F)
Storage temperature	Storage: -20 °C to 125 °C (-4 °F to 257 °F)
Humidity	10-90% operating 5-95% non-operating
Supply Operating voltage	4.35 to 5.25 Volts
I/O Voltage	1.8V or 3.3V
Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)	(Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)
Mode	Power Consumption, Typical
Polling	7.3 mA
Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA
Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Technical Specifications – Networking

Intel® I226-LM 2.5 Gigabit Network Connection LOM (vPro)

Connector	RJ-45
System Interface	PCI(Intel proprietary) + SMBus
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) 4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126) 5. Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 & 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only) Jumbo Frame 9K
Performance	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000Mbp Full Run: 1000mW 2500Mbp Full Run: 4500mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))



Technical Specifications – Networking

Security & Manageability		Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status Intel® vPro™ support with appropriate Intel® chipset components
Intel® I226V 2.5 Gigabit Network Connection LOM (non-vPro)		
Connector	RJ-45	
System Interface	PCI(Intel proprietary) + SMBus	
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) 4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126) 5. Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10& 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T	
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only) Jumbo Frame 9K	
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000Mbp Full Run: 1000mW 2500Mbp Full Run: 4500mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW	
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	

Technical Specifications – Networking

IT Manageability

Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))

Comprehensive diagnostic and configuration software suite
Virtual Cable Doctor for Ethernet cable status

Security & Manageability

Intel® non-vPro™ support with appropriate Intel® chipset components

Technical Specifications – Power

POWER

Power supply availability may vary by country.

HP 200W Slim 4.5 mm PFC Right Angle Smart (3-pin) AC Power Adapter Eris+

Dimensions	6.496 x 3.11 x 1.0 in (16.5x7.9x2.54cm)
Weight	530g(+/-10g) (Not including power cord. Power cord varies by country.)
Input Voltage	100-240Vac
Input Efficiency	88 % at 115 Vac and 89 % at 230Vac
Input frequency range	47-63 Hz
Input AC current	Max. 3.0 A at 90 Vac
Output	
Output power	200W
DC output	19.5V
Hold-up time	100% load 5ms at 115 Vac input
Output Over Current	< 21.0A
Protection	
Connector	C14
Connector	4.5mm Barrel Type
Environmental Design	
Operating temperature	32oF to 95oF (0oto 35oC)
Non-operating (storage) temperature	-4oF to 185oF (-20oto 85oC)
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	20% to 95%
Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1 and IEC62368-1: 2018, EN62368-1:2014+A11, UL62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC and CECP, CU(EAC), EAEU, KCC(Safety+EMC), NOM-001 and 029 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia GEMS and RCM, BIS, BSMI, UAE, UKCA DoC

Technical Specifications – Power

HP 280W Standard 4.5 mm Right Angle Smart (3-pin) AC Power Adapter Bowser+

Dimensions	7.087 x 3.465 x 1.0 in (18.0x8.8x2.54cm)
Weight	730g(+/-10g) (Not including power cord. Power cord varies by country.)
Input Voltage	100-240Vac
Input Efficiency	89 % at 115Vac/230Vac
Input frequency range	47-63 Hz
Input AC current	Max. 4.0 A at 90 Vac
Output	
Output power	280W
DC output	20.0V
Hold-up time	100% load 10ms at 115 Vac input
Output Over Current	< 28.0A
Protection	
Connector	C14
Connector	4.5mm Barrel Type
Environmental Design	
Operating temperature	32oF to 95oF (0oto 35oC)
Non-operating (storage) temperature	-4oF to 185oF (-20oto 85oC)
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	20% to 95%
Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1, IEC 62368-1:2014 and IEC62368-1: 2018, EN62368-1:2020+A11, UL62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, CU(EAC), KCC(Safety+EMC), NOM-001 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia RCM, BIS, BSMI, UAE, UKCA DoC

HP 330W Standard 4.5 mm PFC Straight Smart (3-pin) AC Power Adapter Luigi

Dimensions	7.87 x 3.54 x 1.0 in (20.0x9.0x2.54cm)
Weight	770g(+/-10g) max (Not including power cord. Power cord varies by country.)
Input Voltage	100-240Vac
Input Efficiency	89 % at 115Vac/230Vac
Input frequency range	47-63 Hz
Input AC current	Max. 4.2 A at 90 Vac
Output	
Output power	330W
DC output	20.0V
Hold-up time	100% load 10ms at 115 Vac input



Technical Specifications – Power

Output Over Current Protection	< 25.0A
Connector	C14
Connector	4.5mm Barrel Type
Environmental Design	
Operating temperature	32°F to 95°F (0°C to 35°C)
Non-operating (storage) temperature	-40°F to 185°F (-20°C to 85°C)
Non-operating (storage) temperature	
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	20% to 95%
Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1, IEC 62368-1:2014 and IEC62368-1: 2018, EN62368-1:2020+A11, UL62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, CU(EAC), KCC(Safety+EMC), NOM-001 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia RCM, BIS, BSMI, UAE, UKCA DoC

GE 99Whr Long Life Polymer Fast Charge 8 cell Battery

Weight	0.41kg +/- 10g(0.90 lb)
Cells/Type	8 cell Lithium-Ion Polymer cell /574269
Energy	
Voltage	15.56V
Amp-hour capacity	6.37Ah
Watt-hour capacity	99.1Wh
Temperature	
Operating (Charging)	0° to 45° C (32° to 113° F)
Operating (Discharging)	-10° to 65° C (14° to 149° F)
Fuel Gauge LED	
Warranty	
Optional Travel Battery	
Available	

Technical Specifications – Audio

AUDIO

HD Stereo Codec

Realtek ALC3315

Audio I/O Ports

Support 3.5mm Headset: CTIA only and Headphone-out

Internal Speaker Amplifier

Texas Instruments digital input Class-D smart audio amplifiers

Multi-streaming Capable

Playback multi-streaming can be enabled in the audio control panel to allow independent audio. Following MSFT Behaviour

Sampling

DAC:48kHz 16bits~24bits

ADC:44.1k~48kHz 16bits~24bits

Analog Audio

Support 3.5mm Headset: CTIA only and Headphone-out

Internal Speaker

Yes

Technical Specifications – Fingerprint Reader

FINGERPRINT READER

Sensor vendor	Synaptics FS7614
Sensor type	Capacitive
DPI resolution	363 DPI
Scan area	104 x 86 pixels
False Rejection Rate	<3%
False Acceptance Rate	< 0.001%
Mobile Voltage Operation	3.0V to 3.6V
Operating Temperature	0°~60°C
Current Consumption Image	100mA max
Low Latency Wait For Finger	260uA
Capture Rate	Image transmitter output frequency 9.6MHz
ESD Resistance	IEC 61000-4-2 4B (+15KV)
Detection Matrix	363 dpi / 7.4x6mm sensor area
Footnotes	

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:																				
	<ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• US Federal Energy Management Program (FEMP)• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.• TCO Certified• China Energy Conservation Program (CECP)• China State Environmental Protection Administration (SEPA)• Taiwan Green Mark• Korea Eco-label• Japan PC Green label*																				
Sustainable Impact Specifications	<ul style="list-style-type: none">• Product Carbon Footprint• At least 30% ocean bound plastic in the speaker¹• At least 30% post-consumer recycled plastic²• At least 85% recycled metal³• Low Halogen⁴• 100% of HP paper-based packaging is from recycled or certified sustainable sources⁵• Bulk packaging available																				
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.																				
Energy Consumption (in accordance with US ENERGY STAR® test method)	<table><thead><tr><th></th><th>115VAC, 60Hz</th><th>230VAC, 50Hz</th><th>100VAC, 50Hz</th></tr></thead><tbody><tr><td>Normal Operation (Short idle)</td><td>8.01 W</td><td>7.84 W</td><td>8.16 W</td></tr><tr><td>Normal Operation (Long idle)</td><td>N/A</td><td>N/A</td><td>N/A</td></tr><tr><td>Sleep</td><td>1.79 W</td><td>1.82 W</td><td>1.87 W</td></tr><tr><td>Off</td><td>0.40 W</td><td>0.40 W</td><td>0.39 W</td></tr></tbody></table>		115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	Normal Operation (Short idle)	8.01 W	7.84 W	8.16 W	Normal Operation (Long idle)	N/A	N/A	N/A	Sleep	1.79 W	1.82 W	1.87 W	Off	0.40 W	0.40 W	0.39 W
	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz																		
Normal Operation (Short idle)	8.01 W	7.84 W	8.16 W																		
Normal Operation (Long idle)	N/A	N/A	N/A																		
Sleep	1.79 W	1.82 W	1.87 W																		
Off	0.40 W	0.40 W	0.39 W																		

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.



Technical Specifications – Environmental

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	27 BTU/hr	27 BTU/hr	28 BTU/hr
Normal Operation (Long idle)	N/A	N/A	N/A
Sleep	6.1 BTU/hr	6 BTU/hr	6.4 BTU/hr
Off	1.4 BTU/hr	1 BTU/hr	1.3 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{Wad} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.6	14.6
Fixed Disk – Random writes	3.5	24.0
Optical Drive – Sequential reads	5.0	35.8
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the	
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.	
Additional Information	<ul style="list-style-type: none"> This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 98.3% recycle-able when properly disposed of at end of life. 	

Packaging Materials	External:	PAPER/Corrugated	39 g
		PAPER/Molded Pulp	240 g
		PAPER/Paper	31 g

The plastic packaging material contains at least 0.0% recycled content.

The corrugated paper packaging materials contains at least 57.9% recycled content.



Technical Specifications – Environmental

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [HP RoHS position statement](#).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

<https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c05998906>):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Technical Specifications – Environmental

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:

<https://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c05403198> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: [HP Product Disassembly Instruction Website](#). These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

- Sustainable Impact Report
 - <https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843>
- Eco-label certifications
 - https://www.hp.com/us-en/sustainable-impact/document-reports.html#filters_documents_reports--=document_type-type_energy_star,type_epeat,type_tcolISO
- ISO 14001 certificates
 - <https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932>

Footnotes

1. Percentage of ocean-bound plastic contained in each component varies by product. Ocean Bound plastic is expressed as a percentage of the total weight plastic. Ocean Bound plastic is based on the definition set by the UL2809 standard.
2. Recycled plastic is expressed as a percentage of the total weight plastic. Post-consumer recycled is based on the definition set in the EPEAT standard for computers, IEEE 1680.1-2018 standard.
3. Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.
4. External power supplies, WWAN modules, power cords, cables and peripherals excluded. Service parts obtained after purchase may not be Low Halogen.
5. HP paper and fiber-based packaging for PCs, displays, home and office print, and supplies is reported by suppliers as recycled or certified, with a minimum of 97% by volume verified by HP.



Technical Specifications – Environmental

Packaging is the box that comes with the product and all paper-based materials inside the box. Packaging for personal systems accessories and spare parts is not included. Plastic cushions are made from >90% recycled plastic.

Options and Accessories (sold separately and availability may vary by country)

AFTER MARKET OPTION

Type	Description	Part#
Docking	HP Thunderbolt 4 Ultra 280W G6 Dock	AW5M5UT
	HP Thunderbolt 280W G4 Dock w/Combo Cable	4J0G4AA
	HP Thunderbolt 280W G4 Dock w/Combo Cable	4J0G4ET
	HP Thunderbolt 280W TAA G4 Dock w/Combo Cable	4J0J9AA
Input/Output	HP USB-C to USB-C 100W Cable	5AR72AA
Keyboard/Mouse	HP 320K Wired Keyboard	9SR37AA
	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 455 Programmable USB Wireless Keyboard (Bulk Qty.12)	4R177A6
	HP 965 BLK Ergonomic Wireless Keyboard	7E756AA
	HP 475 Dual-Mode Wireless Keyboard	7N7B9AA
	HP 475 Dual-Mode Wireless Keyboard	7N7B9UT
	HP 405 Multi-Device Backlit Wired Keyboard	7N7C1AA
	HP 405 Multi-Device Backlit Wired Keyboard	7N7C1UT
	HP 435 Programmable Bluetooth Wireless Keypad	7N7C3AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10)	4R009A6
	HP Wired 320M Mouse	9VA80AA
	HP Multi-Device 635 Black Wireless Mouse	1D0K2AA
	HP Creator 935 Black Wireless Mouse	1D0K8AA
	HP 235 Slim Wireless Mouse	4E407AA
	HP 235 Slim Wireless Mouse	4E407UT
	HP 435 Multi-Device Wireless Mouse	3B4Q5UT
	HP 715 Rechargeable Multi-Device Bluetooth Mouse	6E6F0AA
	HP 925 Ergonomic Vertical Wireless Mouse	6H1A5AA
	HP 695 Qi-Charging Wireless Mouse	8F1Y4AA
	HP Tilt Ergonomic Mouse 725M	BH0Z5AA
Hub	HP USB-C to USB-A Hub	Z6A00AA
	HP Portable USB-C Hub	B8SU8UT
	HP Portable USB-C Hub	B8SV8AA
Audio	HP USB G2 Stereo Headset	428H5AA
	HP USB G2 Stereo Headset	428K6AA
	HP USB G2 Stereo Headset	428K6PT



Options and Accessories (sold separately and availability may vary by country)

Power	HP 330W Smart AC Adapter	BF7A6AA
	HP 330W Smart AC Adapter	BF7C7AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP Sure Key Cable Lock	6UW42AA
	HP Nano Combination Cable Lock	63B28AA
	HP Essential Nano Combination Cable Lock	63B31AA

CHANGE LOG

Date of change	Version History		Description of change
June 2, 2025	From v1 to v2	Changed	Format
June 9, 2025	From v2 to v3	Changed	ENVIRONMENTAL DATA section
July 15, 2025	From v3 to v4	Changed	Right view section
July 23, 2025	From v4 to v5	Changed	POWER, Docking (Sold Separately) sections
August 4, 2025	From v5 to v6	Changed	SOFTWARE AND SECURITY section
October 1, 2025	From v6 to v7	Changed	MEMORY section
November 11, 2025	From v7 to v8	Changed	SOFTWARE AND SECURITY section
December 17, 2025	From v8 to v9	Update	MEMORY section updated

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